**Application No.: 10/725,384** 

## **REMARKS**

Claims 1 through 5 and 7 through 11 are now pending in this application. In response to the final Office Action, dated November 4, 2005, a Request for Continued Examination is filed herewith in a separate paper. Claim 1 has been amended to include the recitation of now cancelled claim 6. New claims 7 through 11 have been added. Care has been taken to avoid the addition of new matter.

Claims 1 through 3 were rejected under 35 U.S.C. § 102(b) as being anticipated by JP-05206298 (Mouri, Tsuromi). Claim 4 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Mouri in view of Iku. Claim 5 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Mouri in view of Iku and Yamazuki. These rejections are now moot.

Claim 6, dependent from claim 1, was indicated to be allowable if rewritten in appropriate independent form. Claim 1 has been amended to add the recitation of now cancelled claim 6. Claim 1, therefore, is a rewrite of claim 6 in appropriate independent form and thus is allowable. Claims 2 through 5 are dependent from claim 1 and thus also are allowable.

New claims 8 through 11 are dependent from new independent claim 7. Claim 7 is supported by Fig. 1 and its accompanying description in the disclosure. The claimed first wiring is exemplified by 11A, the first interlayer film exemplified by 13, the plurality of vias exemplified by the openings in film 13 that surround interconnections 11B and 15, and the second interlayer film exemplified by 17. The second interlayer film extends in the longitudinal direction of the via.

It is submitted that Mouri neither discloses nor suggests this claimed structure. As shown in Fig. 1 of Mouri, reproduced in the Office Action, an electrode wiring film (3) has a dummy

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via hole (5). There is no second interlayer film, formed in a first interlayer film in the vicinity of a via, and extending in the longitudinal direction of the via.

Mouri describes the disclosed structure as follows: "Disconnection of electrode wiring depends on the length or the width of an electrode wiring line. The present invention focuses on the length of an electrode wiring line, and provides electrode wiring strong against tensile stress generated in the wiring by shortening the electrode wiring, preventing disconnection of the electrode wiring." Mouri thus forms the dummy via hole (5) in the electrode wiring film (3) to provide electrode wiring that is strong against tensile stress. Both the structural configuration and the purpose of the structure are completely different from the invention recited in claims 7 through 11. Mouri does not disclose that the dummy via hole (5) is a stress concentration portion. The intent of Mouri is to shorten the length of the electrode wiring film (3) by forming the dummy via hole (5) in the electrode wiring film. By shortening the length of the electrode wiring film (3), the amount of distortion caused when tensile stress is generated in the electrode wiring film (3) is reduced, and thus disconnection is prevented.

The structure recited in claims 7 through 11 are not disclosed in the Iku and Yamazuki references. As the claimed structure would not have been suggested by the reference teachings, taken individually or in combination, it is submitted that claims 7 through 11 are patentably distinguishable.

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Accordingly, allowance of the application is respectfully solicited. To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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